

IN THE CLAIMS:

Please amend claims 1, 2, 8, 12, 14, 16, and 18, as indicated.

A2
1. (Amended) An apparatus comprising:

a bond wire;

an insulating material coating said bond wire; and

a first end of said bond wire connected to a bond pad.

A3
2. (Amended) The insulated bond wire of claim 1 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.

A3
8. (Amended) An integrated circuit comprising:

a first bond wire;

an insulating material coating said first bond wire;

a first end of said first bond wire connected to a bond pad; and

a second bond wire crossing said first bond wire.

A4
12. (Amended) The integrated circuit assembly of claim 11 wherein said substrate is selected from a group consisting of printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

A5
14. (Amended) The integrated circuit assembly of claim 11 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.

A6

16. (Amended) The integrated circuit assembly of claim 15 wherein said substrate is selected from a group consisting of printable circuit boards, aluminum lead frames, and fine pitch ball grid arrays.

A7

18. (Amended) The integrated circuit assembly of claim 15 wherein said bond wire material is selected from a group consisting of gold, silver, aluminum, and copper.